(19) Weltorganisation für geistiges Eigentum Internationales Büro



(43) Internationales Veröffentlichungsdatum 15. April 2004 (15.04.2004)

(10) Internationale Veröffentlichungsnummer WO 2004/031437 A1

(51) Internationale Patentklassifikation?: 16/27, 30/00

C23C 16/02,

(21) Internationales Aktenzeichen:

PCT/EP2003/010735

(22) Internationales Anmeldedatum:

26. September 2003 (26.09.2003)

(25) Einreichungssprache:

Deutsch

(26) Veröffentlichungssprache:

Deutsch

(30) Angaben zur Priorität: 102 45 300.4 27. September 2002 (27.09.2002) DE

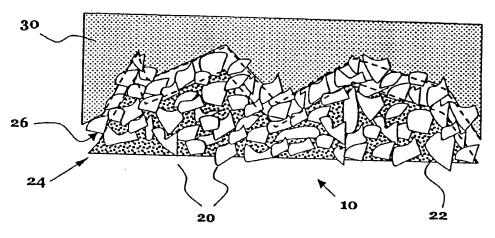
(71) Anmelder (für alle Bestimmungsstaaten mit Ausnahme von US): CEMECON AG [DE/DE]; Adenauerstrasse 20B1, 52146 Würselen (DE).

- (72) Erfinder; und
- (75) Erfinder/Anmelder (nur für US): GUSSONE, Joachim [DE/DE]; Nordhoffstrasse 25, 52074 Aachen (DE). FRANK, Martin [DE/DE], An den Frauenbrüdern 6, 52064 Aachen (DE). BREIDT, Dirk [DE/DE]; Erkelenzer Strasse 86, 41844 Wegberg (DE).
- (74) Anwalt: WENZEL & KALKOFF; Flasskuhle 6, 58452 Witten (DE).
- (81) Bestimmungsstaaten (national): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

[Fortsetzung auf der nächsten Seite]

(54) Title: COATING METHOD AND COATED ELEMENT

(54) Bezeichnung: BESCHICHTUNGSVERFAHREN UND BESCHICHTETER KÖRPER



(57) Abstract: Disclosed are an element comprising a hard metal substrate (10) and a diamond layer (30), and a method for coating a hard metal substrate (10). Said hard metal substrate is provided with hard material particles (20) and surrounding binding material (22). The hard material particles (20) are surrounded by binding material (22) in a first area (24) comprising intact hard metal. The transition region of the first area (24) encompasses a deep profile having recesses (18) and elevations (16). The diamond layer (30) is braced with the substrate material (10) with the aid of said deep profile, portions of the diamond layer (30) being disposed deeper within the substrate (10) than elevations (16) of the first area (24). Said structure is obtained by means of a pretreatment process in which a hard metal substrate (10) is first subjected to selective etching in order to remove the binding material (22). A porous zone having a deep profile is formed. The hard material particles located within the porous zone (12) are removed by means of microbeams or a second, WC-selective etching step. A cobalt concentration on the surface is finally removed in a Co-selective etching step, and the substrate (10) is coated with a diamond layer by means of CVD.